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<b>Membership Task Force</b>	Paula Hunter, NFC Forum		
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Wireless Charging Task Force	Nobuyoshi Hayashi, ROHM	Erwan Le Fer, Micropross (Vice-Chair)	
NFC Devices Working Group	Klaus Roehrle, Sony	John Hillan, Qualcomm (Vice-Chair)	LLCP: NCI: Jingqing Mei, Huawei T1T: T2T: Henk Dannenberg, NXP T3T: Klaus Roehrle, Sony T4T: Henk Dannenberg, NXP T5T: Erich Reisenhofer, NXP
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as of January 2019

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